L Number	Hits	Search Text	DB	Time stamp
16	3	((chip or die) and (crack or cracking or bulging or bulge)) near adhesive	USPAT	2003/04/07 01:49
17	3	((chip or die) and (bulging or bulge or crack or cracking)) near adhesive	USPAT	2003/04/07 03:19
18	492	((chip or die) with ((bend or bending or bulging or bulge or crack or cracking) and tape)) and adhesive	USPAT	2003/04/07 00:51
19	99	(((chip or die) with ((bend or bending or bulging or bulge or crack or cracking) and tape)) and adhesive) and (adhesive near (chip or die))	USPAT	2003/04/07 00:52
20	9	((chip or die) and (interposer or buffer)) near adhesive	USPAT	2003/04/07 01:03
21	411	(chip or die) and (tape adj substrate)	USPAT	2003/04/07 01:04
22	39	((chip or die) and (tape adj substrate)) and ((crack or cracking or bulging or bulge or bend or bending) with (chip or die or semiconductor or device))	USPAT	2003/04/07 01:19
23	18	(((chip or die) and (tape adj substrate)) and ((crack or cracking or bulging or bulge or bend or bending) with (chip or die or semiconductor or device))) and reflow	USPAT	2003/04/07 01:10
24	3984	((crack or cracking or bulging or bulge or bend or bending) near (chip or die or semiconductor or device))	USPAT	2003/04/07 02:46
25	60	(((crack or cracking or bulging or bulge or bend or bending) near (chip or die or semiconductor or device))) and ((chip or die) near adhesive)	USPAT	2003/04/07 01:31
26	20	((((crack or cracking or bulging or bulge or bend or bending) near (chip or die or semiconductor or device))) and ((chip or die) near adhesive)) and reflow	USPAT	2003/04/07 01:36
27	9	(((((crack or cracking or bulging or bulge or bend or bending) near (chip or die or semiconductor or device))) and ((chip or die) near adhesive)) and reflow) and moisture	USPAT	2003/04/07 01:46
28	1	("6541844").PN.	USPAT	2003/04/07 01:46
29	31	((crack or cracking or bulging or bulge or bend or bending) and substrate) near (polyimide or tape)	USPAT	2003/04/07 01:56
30	22	(((crack or cracking or bulging or bulge or bend or bending) and substrate) near (polyimide or tape)) and (@ad<19980728)	USPAT	2003/04/07 02:37
31	9	((((crack or cracking or bulging or bulge or bend or bending) and substrate) near (polyimide or tape)) and (@ad<19980728)) and (chip or die)	USPAT	2003/04/07 01:54
32	4	("5898213" | "5951304" | "6232650" | "6285086").PN.	USPAT	2003/04/07 01:53
33	1299	(chip or die) and ((tape or polyimide) near substrate)	USPAT	2003/04/07 01:55
34	903	((chip or die) and ((tape or polyimide) near substrate)) and (@ad<19980728)	USPAT	2003/04/07 02:48
35	206	(((chip or die) and ((tape or polyimide) near substrate)) and (@ad<19980728)) and ((chip or die) near ((tape or polyimide) or substrate))	USPAT	2003/04/07 01:56
36	71	((((chip or die) and ((tape or polyimide) near substrate)) and (@ad<19980728)) and ((chip or die) near ((tape or polyimide) or substrate))) and (crack or cracking or bulging or bulge or bend or bending)	USPAT	2003/04/07 01:57

37	22	(((((chip or die) and ((tape or polyimide) near substrate)) and (@ad<19980728)) and ((chip or die) near ((tape or polyimide) or substrate))) and (crack or cracking or bulging or bulge or bend or bending)) and reflow	USPAT	2003/04/07 02:06
38	1	("5261593").PN.	USPAT	2003/04/07 02:11
39	0	("L36 and (solder adj ball$2)").PN.	USPAT	2003/04/07 02:11
40	25	(((((chip or die) and ((tape or polyimide) near substrate)) and (@ad<19980728)) and ((chip or die) near ((tape or polyimide) or substrate))) and (crack or cracking or bulging or bulge or bend or bending)) and (solder adj ball$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 02:12
41	22	((((((chip or die) and ((tape or polyimide) near substrate)) and (@ad<19980728)) and ((chip or die) near ((tape or polyimide) or substrate))) and (crack or cracking or bulging or bulge or bend or bending)) and (solder adj ball$2)) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 02:34
42	122	(chip or die) and ((tape or polyimide) near (interposer or buffer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 02:36
44	2	(((chip or die) and ((tape or polyimide) near (interposer or buffer))) and (solder adj ball)) and (@ad<19980728)	USPAT	2003/04/07 02:37
43	20	((chip or die) and ((tape or polyimide) near (interposer or buffer))) and (solder adj ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 02:48
45	3994	((crack or cracking or bulging or bulge or bend or bending) near (prevent or eliminate or stop)) and (chip or die or device)	USPAT	2003/04/07 02:51
46	3296	(((crack or cracking or bulging or bulge or bend or bending) near (prevent or eliminate or stop)) and (chip or die or device)) and (@ad<19980728)	USPAT	2003/04/07 02:48
47	18	((((crack or cracking or bulging or bulge or bend or bending) near (prevent or eliminate or stop)) and (chip or die or device)) and (@ad<19980728)) and (solder adj ball) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 02:48
48	15	(((crack or cracking or bulging or bulge or bend or bending) and (tape or polyimide)) near (prevent or eliminate or stop)) and (chip or die or device)	USPAT	2003/04/07 03:10
49	1	("5917234").PN.	USPAT	2003/04/07 03:11
50	2	("10173303").PN.	JPO; DERWENT	2003/04/07 03:11
51	49	(tape or polyimide) near (substrate and (permeability or permeable or porous or matrix or comb))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 03:18
52	10	((tape or polyimide) near (substrate and (permeability or permeable or porous or matrix or comb))) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 03:14
53	4	(tape or polyimide) near (substrate and (permeability or permeable))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 03:18

| 54 | 306 | (tape or polyimide) with (substrate and (permeability or permeable)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/07 03:19 |
| 55 | 7 | ((tape or polyimide) with (substrate and (permeability or permeable))) and ((chip or die) and (bulging or bulge or crack or cracking)) | USPAT | 2003/04/07 03:19 |